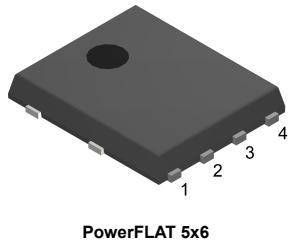
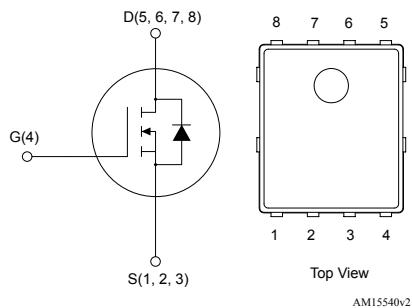


## N-channel 100 V, 0.027 Ω typ., 8 A, SStripFET VII DeepGATE Power MOSFET in a PowerFLAT 5x6 package


**PowerFLAT 5x6**


AM15540v2

### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>	P <sub>TOT</sub>
STL30N10F7	100 V	0.035 Ω	8 A	4.8 W

- Among the lowest R<sub>DS(on)</sub> on the market
- Excellent FoM (figure of merit)
- Low C<sub>rss</sub>/C<sub>iss</sub> ratio for EMI immunity
- High avalanche ruggedness

### Applications

- Switching applications

### Description

This N-channel Power MOSFET utilizes SStripFET F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.



#### Product status link

[STL30N10F7](#)

#### Product summary

Order code	STL30N10F7
Marking	30N10F7
Package	PowerFLAT 5x6
Packing	Tape and reel

## 1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	100	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	30	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	18.2	A
$I_{DM}^{(1)(2)}$	Drain current (pulsed)	120	A
$I_D^{(3)}$	Drain current (continuous) at $T_{pcb} = 25^\circ\text{C}$	8	A
$I_D^{(3)}$	Drain current (continuous) at $T_{pcb} = 100^\circ\text{C}$	5.2	A
$I_{DM}^{(2)(3)}$	Drain current (pulsed)	32	A
$P_{TOT}^{(1)}$	Total power dissipation at $T_C = 25^\circ\text{C}$	75	W
$P_{TOT}^{(3)}$	Total power dissipation at $T_{pcb} = 25^\circ\text{C}$	4.8	W
$T_{stg}$	Storage temperature range	-55 to 175	$^\circ\text{C}$
$T_j$	Operating junction temperature range		

1. This value is rated according to  $R_{thj-c}$ .
2. Pulse width is limited by safe operating area.
3. This value is rated according to  $R_{thj-pcb}$ .

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	31.3	$^\circ\text{C}/\text{W}$
$R_{thj-case}$	Thermal resistance junction-case	2	$^\circ\text{C}/\text{W}$

1. When mounted on an FR-4 board of 1 inch<sup>2</sup>, 2oz Cu,  $t < 10$  s.

## 2 Electrical characteristics

( $T_C = 25^\circ\text{C}$  unless otherwise specified)

**Table 3. On-/off-states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	100			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}$ $V_{GS} = 0,$ $V_{DS} = 100 \text{ V}, T_C = 125^\circ\text{C}$			10	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = +20 \text{ V}$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2.5		4.5	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$		0.027	0.035	$\Omega$

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 50 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0 \text{ V}$	-	920	-	pF
$C_{oss}$	Output capacitance		-	215	-	
$C_{rss}$	Reverse transfer capacitance		-	19	-	
$Q_g$	Total gate charge	$V_{DD} = 50 \text{ V}, I_D = 8 \text{ A},$ $V_{GS} = 0 \text{ to } 10 \text{ V}$ (see <a href="#">Figure 13. Test circuit for gate charge behavior</a> )	-	14	-	nC
$Q_{gs}$	Gate-source charge		-	7	-	
$Q_{gd}$	Gate-drain charge		-	3	-	

**Table 5. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 50 \text{ V}, I_D = 4 \text{ A},$ $R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	9.8	-	ns
$t_r$	Rise time		-	14	-	ns
$t_{d(\text{off})}$	Turn-off delay time	(see <a href="#">Figure 12. Test circuit for resistive load switching times</a> and <a href="#">Figure 17. Switching time waveform</a> )	-	14.8	-	ns
$t_f$	Fall time		-	4.6	-	ns

**Table 6. Source-drain diode**

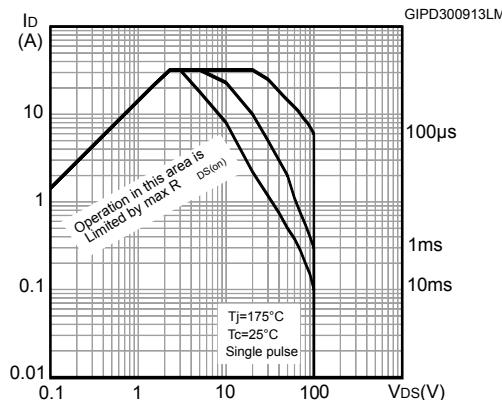
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		8	A
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 8 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.1	V
$I_{SDM}^{(2)}$	Source-drain current (pulsed)		-		32	A
$t_{rr}$	Reverse recovery time	$I_D = 8 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	38		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 80 \text{ V}, T_J = 150 \text{ }^\circ\text{C}$ (see <a href="#">Figure 14. Test circuit for inductive load switching and diode recovery times</a> )	-	29		nC
$I_{RRM}$	Reverse recovery current		-	1.7		A

1. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

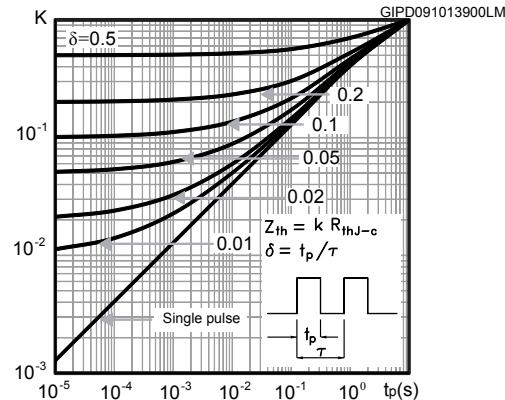
2. Pulse width limited by safe operating area.

## 2.1 Electrical characteristics (curves)

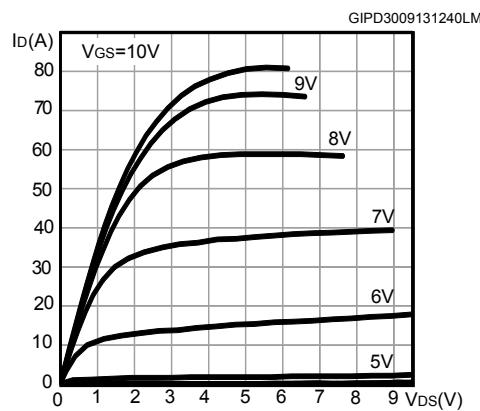
**Figure 1. Safe operating area**



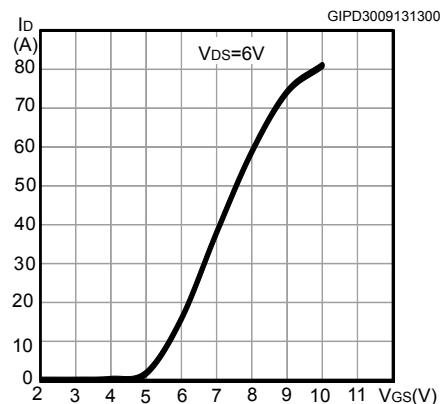
**Figure 2. Thermal impedance**



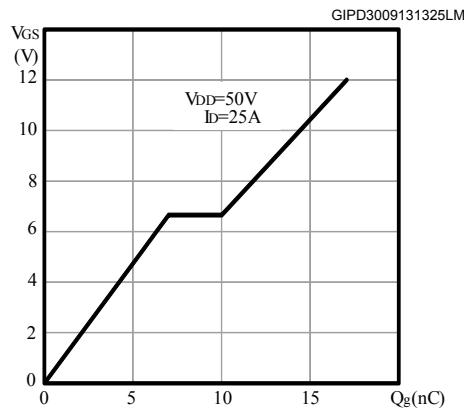
**Figure 3. Output characteristics**



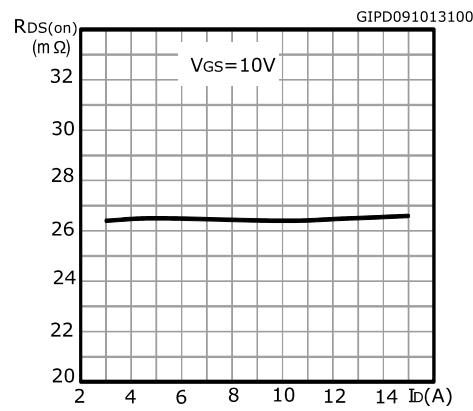
**Figure 4. Transfer characteristics**

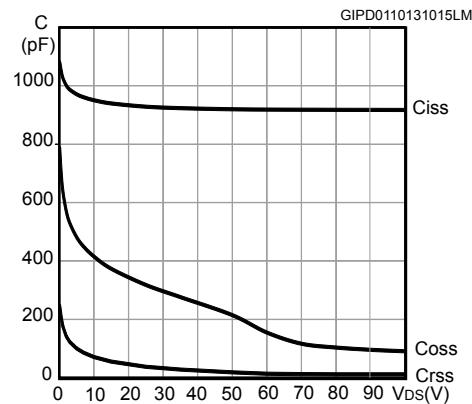
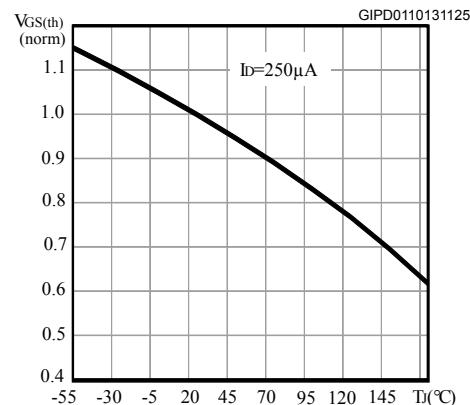
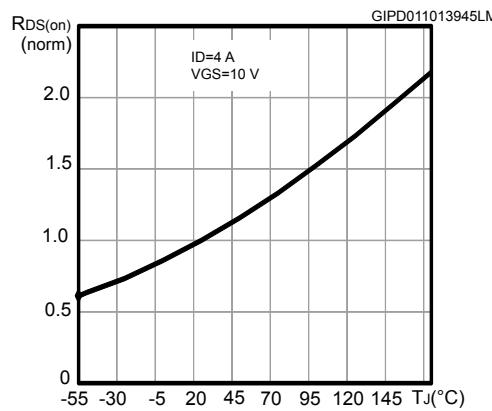
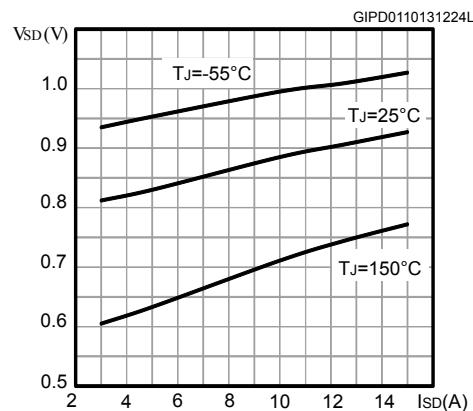
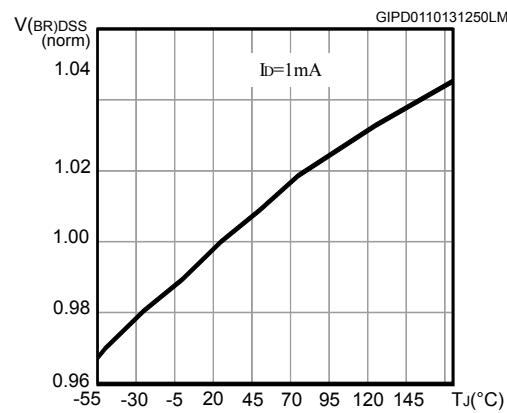


**Figure 5. Gate charge vs gate-source voltage**



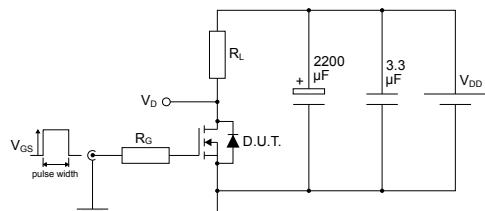
**Figure 6. Static drain-source on-resistance**



**Figure 7. Capacitance variations**

**Figure 8. Normalized gate threshold voltage vs temperature**

**Figure 9. Normalized on-resistance vs temperature**

**Figure 10. Normalized V<sub>(BR)DSS</sub> vs temperature**

**Figure 11. Source-drain diode forward characteristics**


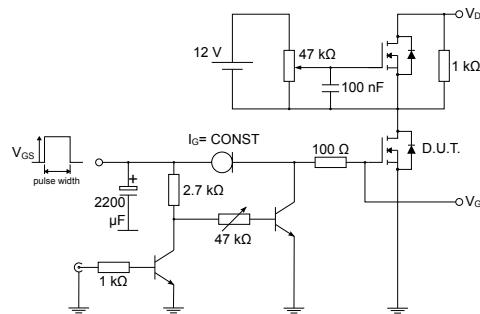
### 3 Test circuits

**Figure 12.** Test circuit for resistive load switching times



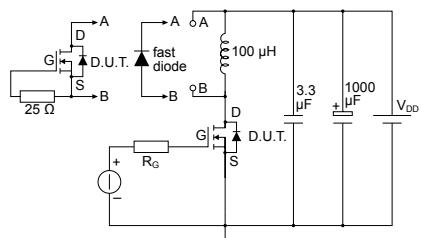
AM01468v1

**Figure 13.** Test circuit for gate charge behavior



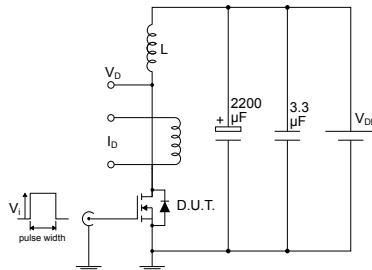
AM01469v1

**Figure 14.** Test circuit for inductive load switching and diode recovery times



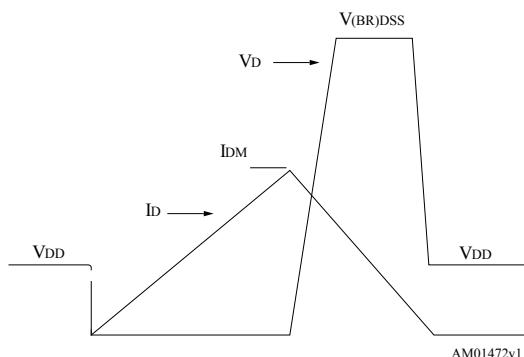
AM01470v1

**Figure 15.** Unclamped inductive load test circuit



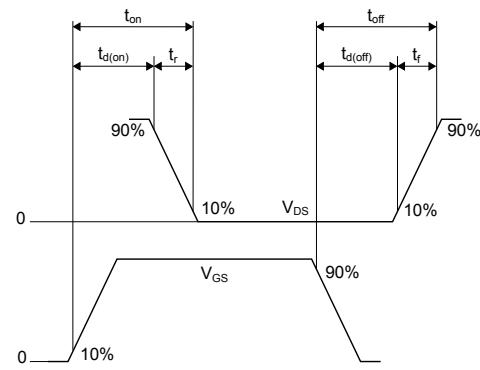
AM01471v1

**Figure 16.** Unclamped inductive waveform



AM01472v1

**Figure 17.** Switching time waveform



AM01473v1

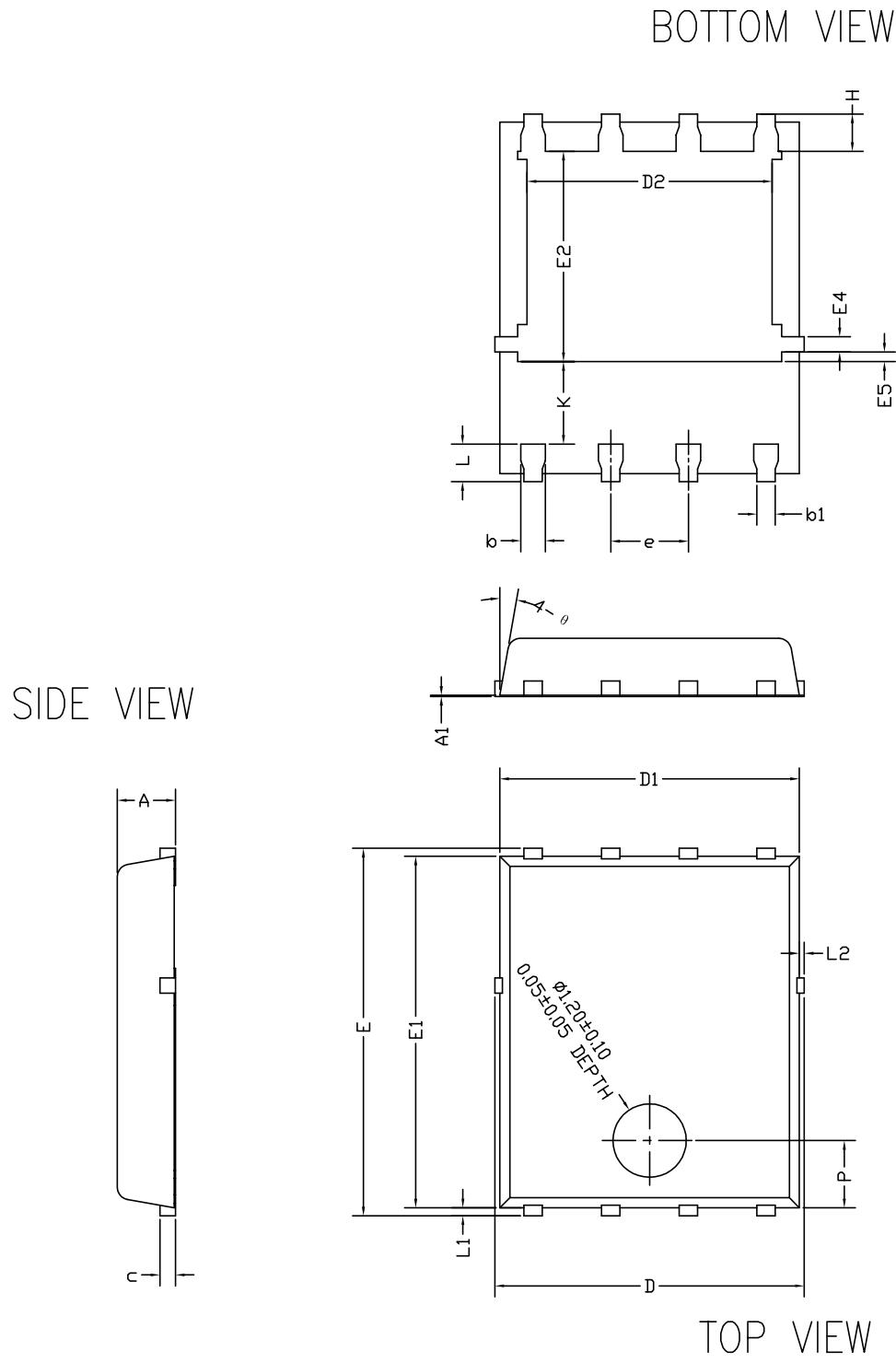
## 4

## Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

## 4.1 PowerFLAT 5x6 type R SUBCON package information

Figure 18. PowerFLAT 5x6 type R SUBCON package outline



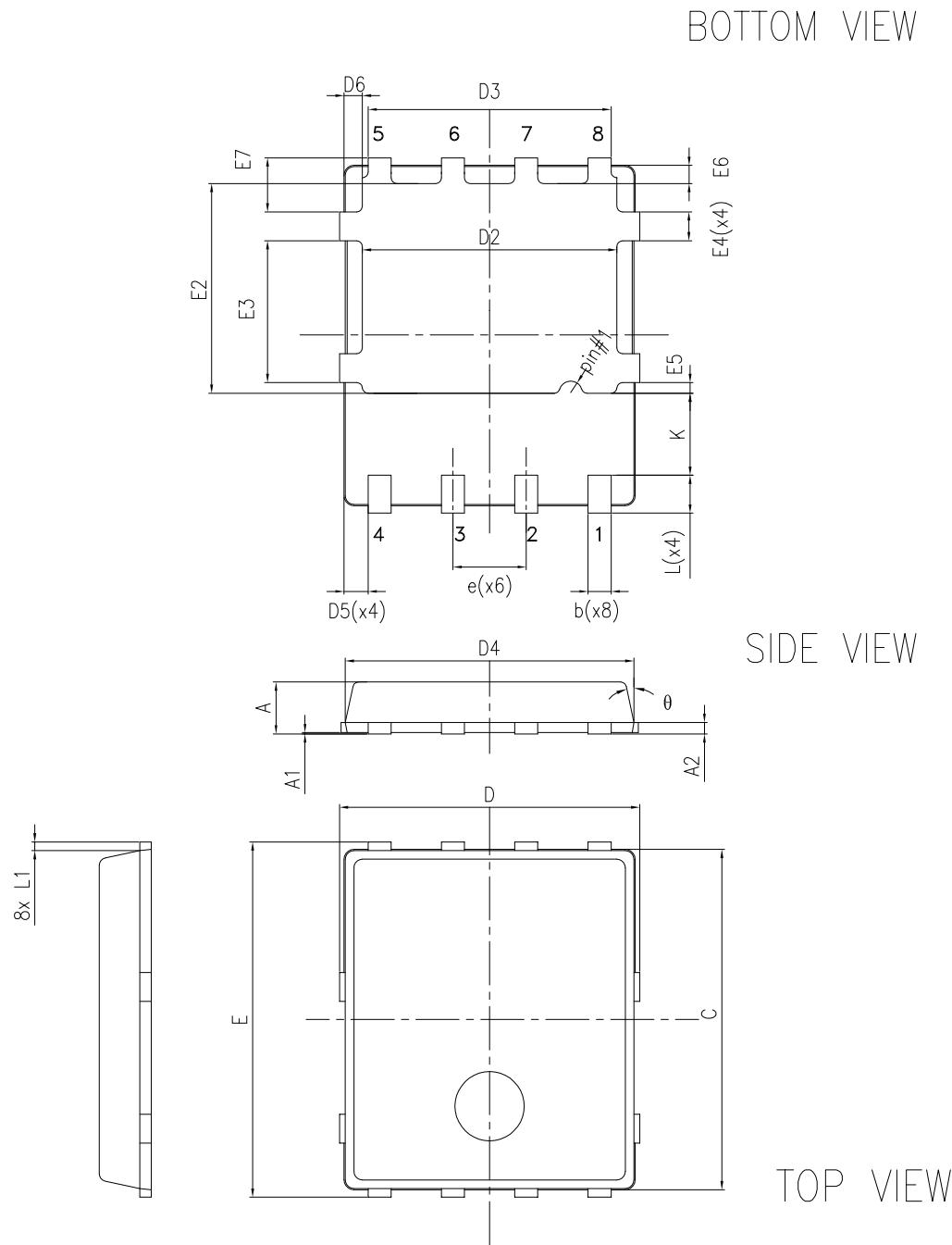
8472137\_SUBCON\_998G\_Type\_R\_REV4

**Table 7. PowerFLAT 5x6 type R SUBCON package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	0.90	0.95	1.00
A1		0.02	
b	0.35	0.40	0.45
b1		0.30	
c	0.21	0.25	0.34
D			5.10
D1	4.80	4.90	5.00
D2	3.91	4.01	4.11
e	1.17	1.27	1.37
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.34	3.44	3.54
E4	0.15	0.25	0.35
E5	0.06	0.16	0.26
H	0.51	0.61	0.71
K	1.10		
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
L2			0.10
P	1.00	1.10	1.20
θ	8°	10°	12°

## 4.2 PowerFLAT 5x6 type R package information

Figure 19. PowerFLAT 5x6 type R package outline

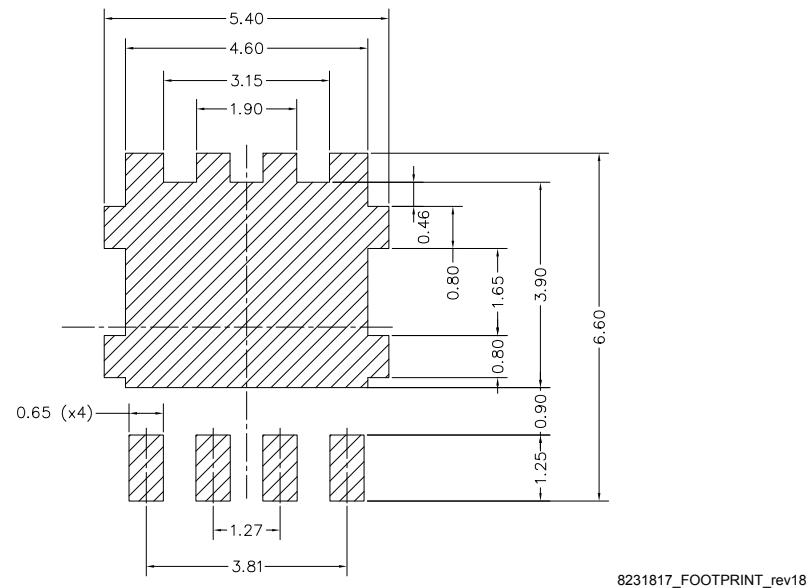


A0ER\_8231817\_Rev15

**Table 8. PowerFLAT 5x6 type R mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.80	6.00	6.20
D	5.00	5.20	5.40
D2	4.15		4.45
D3	4.05	4.20	4.35
D4	4.80	5.00	5.20
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
e		1.27	
E	5.95	6.15	6.35
E2	3.50		3.70
E3	2.35		2.55
E4	0.40		0.60
E5	0.08		0.28
E6	0.20	0.325	0.45
E7	0.75	0.90	1.05
K	1.275		1.575
L	0.60		0.80
L1	0.05	0.15	0.25
θ	0°		12°

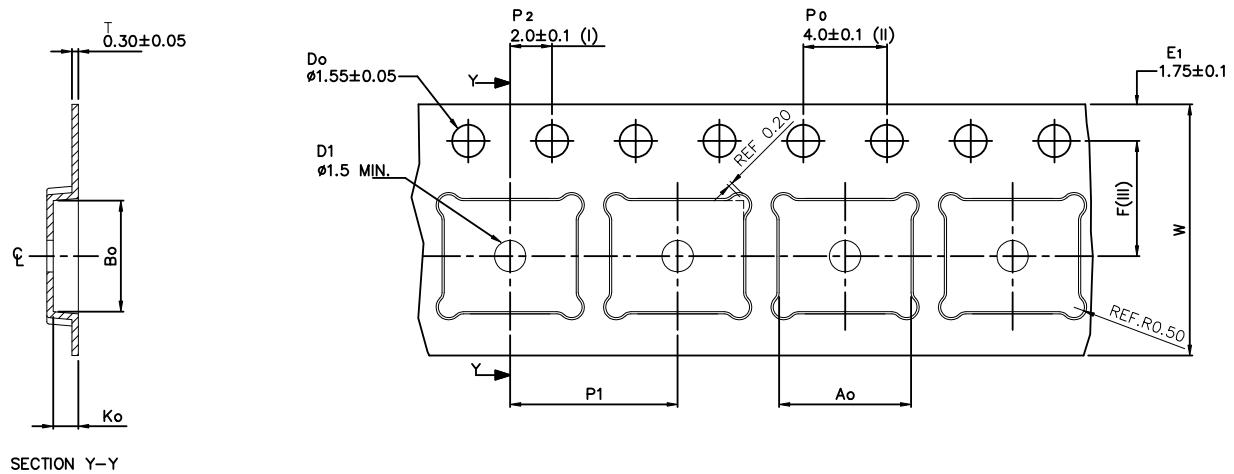
**Figure 20. PowerFLAT 5x6 recommended footprint (dimensions are in mm)**



8231817\_FOOTPRINT\_rev18

## 4.3 PowerFLAT 5x6 packing information

**Figure 21. PowerFLAT 5x6 tape (dimensions are in mm)**



SECTION Y-Y

$A_o$	$6.30 \pm 0.1$
$B_o$	$5.30 \pm 0.1$
$K_o$	$1.20 \pm 0.1$
$F$	$5.50 \pm 0.1$
$P_1$	$8.00 \pm 0.1$
$W$	$12.00 \pm 0.3$

(I) Measured from centreline of sprocket hole to centreline of pocket.

Base and bulk quantity 3000 pcs  
All dimensions are in millimeters

(II) Cumulative tolerance of 10 sprocket holes is  $\pm 0.20$ .

(III) Measured from centreline of sprocket hole to centreline of pocket

8234350\_Tape\_rev\_C

**Figure 22. PowerFLAT 5x6 package orientation in carrier tape**

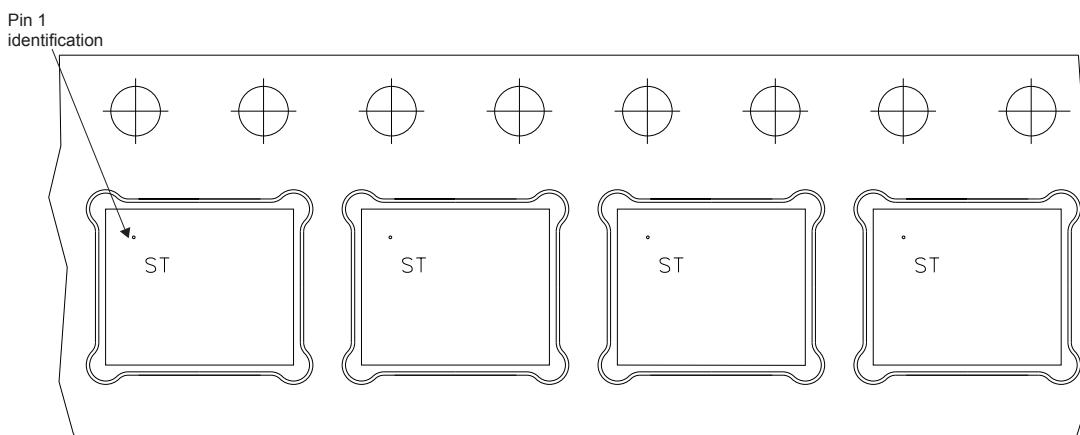
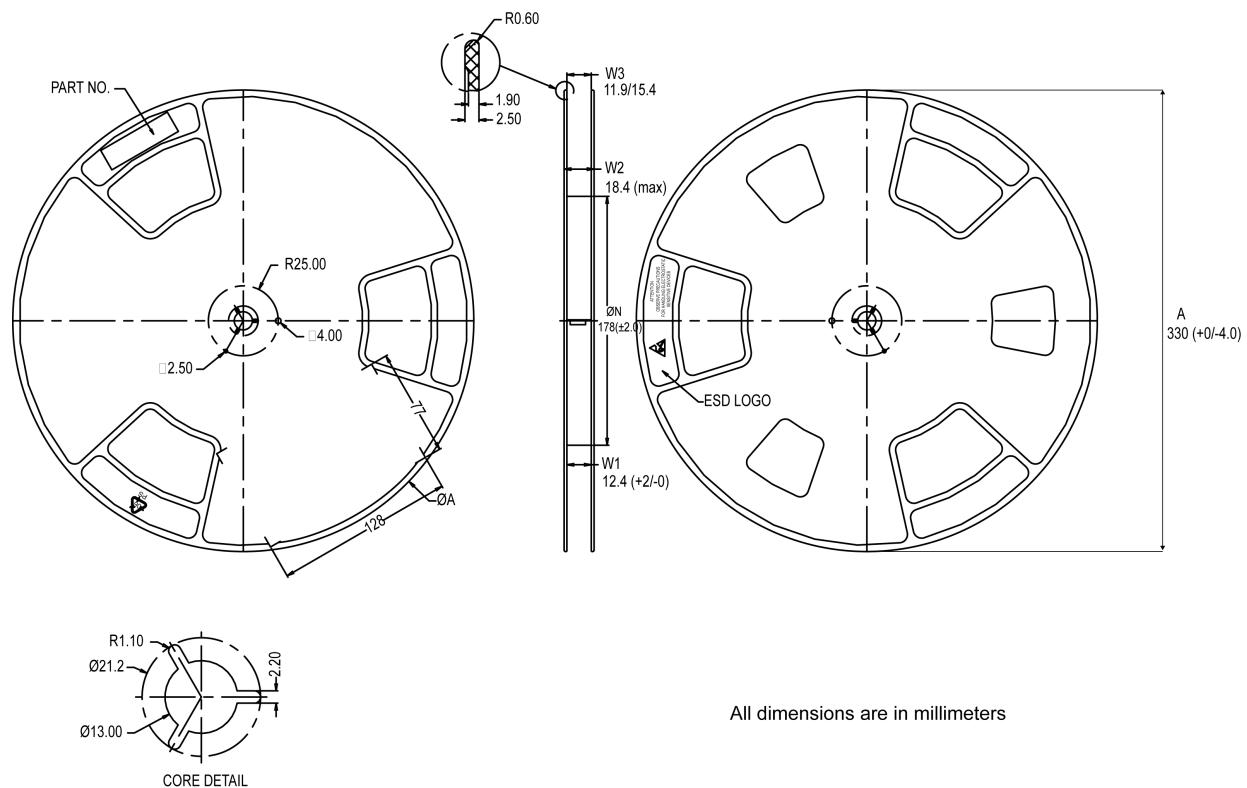


Figure 23. PowerFLAT 5x6 reel



8234350\_Reel\_rev\_C

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
22-Oct-2013	1	First release
25-Nov-2019	2	Added <a href="#">Section 4.1 PowerFLAT 5x6 type R SUBCON package information</a> . Updated <a href="#">Section 4.2 PowerFLAT 5x6 type R package information</a> . Minor text changes.

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